Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	("2001231770").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/09 10:27
S2	4	("2003012863").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/03 16:15
S3	1396	(257/780).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/03 16:21
S4	1105	S3 and @ad<="20030214"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 17:14
S5	233	S3 and @ad>="20030214"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 17:15
S6	2917	(257/737,738).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/08 16:34
S7	1172	(257/701,702).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/06 17:18
S8	831	(chip IC integrated adj chip die) and (substrate) and (adhesive tape sticky adj film) and (stud adj bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/07 12:03
S9	6190	(257/678,787,778).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/07 12:03

S11	2916	S9 and substrate and (tape adhesive) and (die IC integrated adj circuit chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/07 16:25
S13	1909	(257/737).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/07 16:25
S14	98	S13 and pad and (stud adj bump project$2 adj bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/07 16:26
S15	2921	(257/737,738).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/08 10:31
S16	1784	S15 and (stud project$2 bump) and pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/08 12:14
S17	1	("6753612").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/08 16:17
S18	1	("20010027007").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/08 16:18
S19	2921	(257/737,738).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/08 16:36
S20	152	S19 and ((project$2 adj (bump pad)) (stud adj (bump pad)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/08 16:36
S21	2	("6753612").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/09 10:27